

Title (en)

HIGHLY ELECTRICALLY CONDUCTIVE SILVER INK COMPOSITION AND WIRING OBTAINED USING SAME

Title (de)

HOCHELEKTRISCH LEITFÄHIGE SILBERTINTENZUSAMMENSETZUNG UND DAMIT HERGESTELLTE VERDRAHTUNG

Title (fr)

COMPOSITION D'ENCRE ARGENT HAUTEMENT ÉLECTROCONDUCTRICE ET CÂBLAGE OBTENU À L'AIDE DE CETTE DERNIÈRE

Publication

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Application

EP 18922600 A 20180830

Priority

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Abstract (en)

Provided are: a low-cost and highly conductive silver ink composition; and a method for producing wiring using the silver ink composition. A conductive ink composition for screen printing contains a conductive metal particle (A) having an oleic acid surfactant, a non-chlorine-based resin composition (B), and an organic solvent (C), wherein the conductive metal particle (A) is contained in an amount of 45 to 70% by weight with respect to the total ink composition, the non-chlorine-based resin composition (B) has a number average molecular weight of 50,000 or more and is contained in an amount of 5 to 15% by weight with respect to the total ink composition, the organic solvent (C) has a flash point of 75 to 110°C and is contained in an amount of 25 to 50% by weight with respect to the total ink composition, and the ink composition has an ink viscosity of 10 to 25 Pa·s (23°C) at a shear rate of 100 s⁻¹. A method for producing wiring uses the ink composition.

IPC 8 full level

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